

IN THE TITLE:

Please amend the title as follows:

~~LASER DEVICE WHICH IS USED TO PIERCE HOLES IN COMPONENTS OF A~~
~~FLUID INJECTION DEVICE~~LASER DEVICE FOR DRILLING HOLES IN
COMPONENTS OF A FLUID INJECTION DEVICE

IN THE SPECIFICATION:

Page 1, immediately beneath the title, please insert the following new paragraph:

This is a National Phase Application in the United States of International Patent Application No. PCT/EP2004/002408 filed September 3, 2004, which claims priority on European Patent Application No. 03006697.1, filed March 26, 2003. The entire disclosures of the above patent applications are hereby incorporated by reference.

Page 1, before line 1, immediately after the title, please insert the following section heading:

FIELD OF THE INVENTION

Page 1, before paragraph 2, which begins on line 7 and with the words “Currently, various methods are known . . .”, please insert the following section heading:

BACKGROUND OF THE INVENTION

Page 2, before paragraph 4, which begins on line 15 and with the words “The invention therefore concerns. . .”, please insert the following section heading:

SUMMARY OF THE INVENTION

Page 3, before paragraph 4 which begins on line 24 and with the words “The laser machining device. . .”, please insert the following section heading:

BRIEF DESCRIPTION OF THE DRAWINGS

Page 4, before paragraph 1 which begins on line 1 and with the words “With reference to Figures 1 to 3. . .”, please insert the following section heading:

DETAILED DESCRIPTION OF THE ILLUSTRATIVE EMBODIMENTS